



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln Of: NAKAYAMA
Serial No.: 09/593,891
Filed: June 14, 2000
For: SEMICONDUCTOR STORAGE DEVICE
Group: 2815
Examiner: CHU, CHRIS C.

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Assistant Commissioner of Patents
Washington, D.C., 20231

AMENDMENT C

Dear Sir:

This amendment is being filed in response to the Official Action mailed May 3, 2002.

Please amend the application as follows:

IN THE SPECIFICATION:

Please replace the paragraph beginning at page 5, line 17, with the following rewritten paragraph:

--Next, there will be described the second embodiment of the present invention. In the above-described first embodiment, the construction places the rear surface of the upper chip 3 on the surface of the wiring sheet 9. However, in the present embodiment, the upper chip 3 is placed on the wiring sheet 9 in such a way that chip surface is directed to the lower direction while causing inside and outside to be reversed, i.e., upside-down, before placing on the wiring sheet 9. Further, one end of the wiring pattern 14 of the wiring sheet 9 is connected directly to the bonding pad 4 of the upper chip 3, while the other end of the wiring pattern 14 is connected to the bonding pad 7 of the lower chip 2.--

C1